SEIKO EPSON CORPORATION
Sales & Marketing Division.
Device Sales & Marketing Dept.
MICRODEVICES Operations Division.
TD Production Management Control Dept.

## SUB: SPXO SG-210STF Product change notice

Dear Valued Customer.

Thank you for choosing SEIKO EPSON COPRPORATION for your products. EPSON maintains a continuous effort to improve the production and delivery performance of our products. The SG-210STF series of SPXO's will change the location of the sealing material. We appreciate your understanding and approval for this change.

## 1. Affected Products

Product name	P/N
SG-210STF	X1G004171xxxx xx

2. Description of changes

Change Items	Before PCN	After PCN
Appearance	16.0 • F7ZLK	16.0 • F97DK
		With sealing material
Ceramic package	Without sealing material	(Same as other products currently
		in mass production)
		Without sealing material
Lid	With sealing material	(Same as other products currently
		in mass production)
	<standard></standard>	<standard></standard>
	S:±25 x $10^{-6}$ (-20°C~+70°C)	S:±25 x 10 <sup>-6</sup> (-20°C∼+70°C)
	L:±50 x 10 <sup>-6</sup> (-40°C~+85°C)	L:±50 x 10 <sup>-6</sup> (-40°C∼+85°C)
Frequency	Y:±50 x 10 <sup>-6</sup> (-40°C∼+105°C)	Y:±50 x 10 <sup>-6</sup> (-40°C∼+105°C)
Temperature	W:±100 x 10 <sup>-6</sup> (-40°C~+105°C)	W:±100 x 10 <sup>-6</sup> (-40°C∼+105°C)
Characteristics	, ,	,
		<custom>*</custom>
		Z:±100 x 10 <sup>-6</sup> (-40°C~+125°C)
		X:±150 x 10 <sup>-6</sup> (-40°C~+125°C)

For custom specifications, please contact us.



## 3. Reason

By changing the current package supplier, we will ensure a continuous and stable supply system for customers in the future. There will be no change to form, fit, and function of these products.

## 4. Schedule

Sample submission	Reliability data submission	Conversion to new packaged products completed by:
Available now	Available now	March 31, 2021

Please contact us individually for sample delivery schedule.

Please contact your area EPSON device sales office, if you have any concern of this PCN.

Sincerely yours,

Seiko Epson Corporation Microdevices Operations Div.